RL78/G16

RL78/G16 Capacitive Touch Evaluation System Sample Code

Introduction

This document describes the sample code for the RL78/G16 Capacitive Touch Evaluation System

Target Device

RL78/G16 (R5F121BCAFP)

Contents

1. Overview

This sample code is software that operates with capacitive touch in the RL78/G16 Capacitive Touch Evaluation system.

The following is added to the project created by e^2 studio.

- Components generated by the Smart Configurator
- Capacitive touch configuration files and applications tuning with QE for Capacitive Touch (QE)
- LED control application

1.1 Function

The functions are shown below.

1. Capacitive touch function operates all electrodes (3 buttons, slider, wheel) of Capacitive Touch Evaluation Application Board.

2. Since the RL78/G16 does not support monitoring and tuning via an emulator, to monitor and tune with QE, connect to a PC using the USB serial interface on the CPU board and perform serial monitoring and serial tuning.For more information on serial monitoring and serial tuning, refer to QE Help and "8. Setup of QE for Capacitive Touch" in <u>"RL78 Family Using the standalone version of QE to Develop Capacitive Touch Applications (R01AN6574)"</u>.

3. "LED control linked to capacitive touch buttons, sliders and wheels" and "LED control linked to CPU board push buttons" can be switched by setting SW4 on the CPU board and build option: RL78G16_RSSK_TEST. This is because some of the LED control ports on the electrode board and the LED control ports on the CPU board use the same GPIO pins.
   The initial setting performs LED control linked with capacitive touch buttons, sliders, and wheels.

   (1). LED control linked to capacitive touch buttons, sliders and wheels
   Set SW4 on the CPU board to the left.
   Set the build option: RL78G16_RSSK_TEST in qe_touch_sample.c as follows.

   ```
   #define RL78G16_RSSK_TEST   (ELCTRODE_BOARD)
   ```

   (2). LED control linked to CPU board push buttons
   Pressing SW2, LED 2 lights up. Pressing SW3, LED3 lights up.
   Set SW4 on the CPU board to the right.
   Set the build option: RL78G16_RSSK_TEST in qe_touch_sample.c as follows.

   ```
   #define RL78G16_RSSK_TEST   (CPU_BOARD)
   ```

Table 1-1 Settings by LED Control Function

No	Function	SW4 Setting	RL78G16_RSSK_TEST
(1)	LED control linked to capacitive touch (Default setting)	Left	ELCTRODE_BOARD
(2)	LED control linked to CPU board push buttons	Right	CPU_BOARD

2. Operation confirmation conditions

The operation of this sample code has been confirmed the following environment.

Table 2-1 Operation confirmation conditions

Item	Description
MCU	RL78/G16 (R5F121BCAFP)
Operating frequency	16MHz (HOCO 16MHz)
Operating voltage	5.0V SPOR detection voltage : At rising edge TYP. 2.57 V (2.44 V to 2.68 V) At falling edge TYP. 2.52 V (2.40 V to 2.62 V)
Evaluation board	RL78/G16 Capacitive Touch Evaluation System (Product No : RTK0EG0047S01001BJ) • RL78/G16 CPU Board (Product No : RTK0EG0046C01001BJ) • Capacitive Touch Evaluation Application Board — Self-Capacitance Buttons / Wheel / Slider Board (Product No: RTK0EG0019B01002BJ)
Integrated development environment	Renesas e² studio Version 2023-04 (23.04.0)
C Compiler	Renesas CC-RL V1.12 Compile options of optimization: -Odefault
Development Assistance Tool for Capacitive Touch Sensors	QE for Capacitive Touch V3.3.0
Emulator	Renesas E2 Emulator Lite

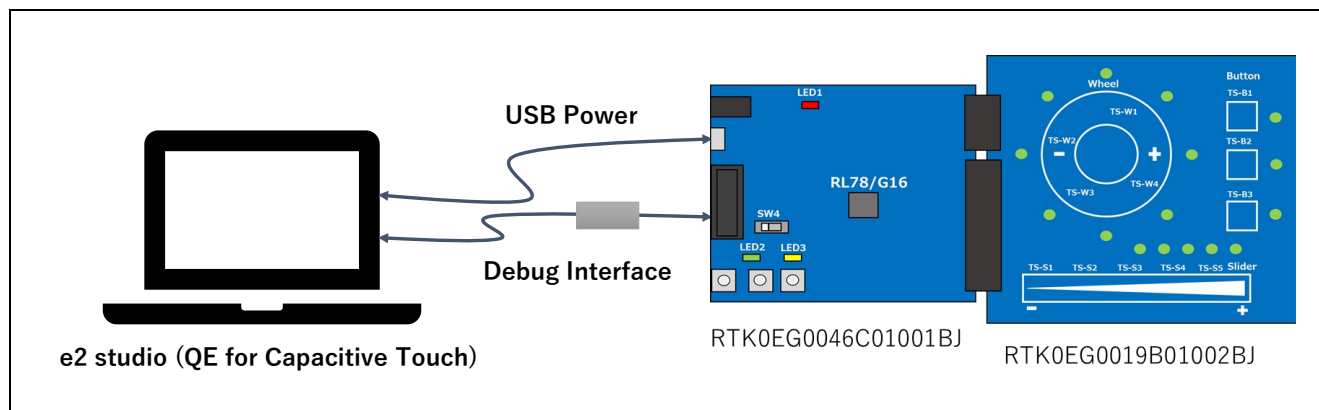Figure 2-1 shows device connection diagram

Figure 2-1 Device Connection Diagram

3. Software specification

3.1   Software structure diagram

Figure 3-1 shows the software structure diagram of this sample code. This software uses components generated by the Smart Configurator.
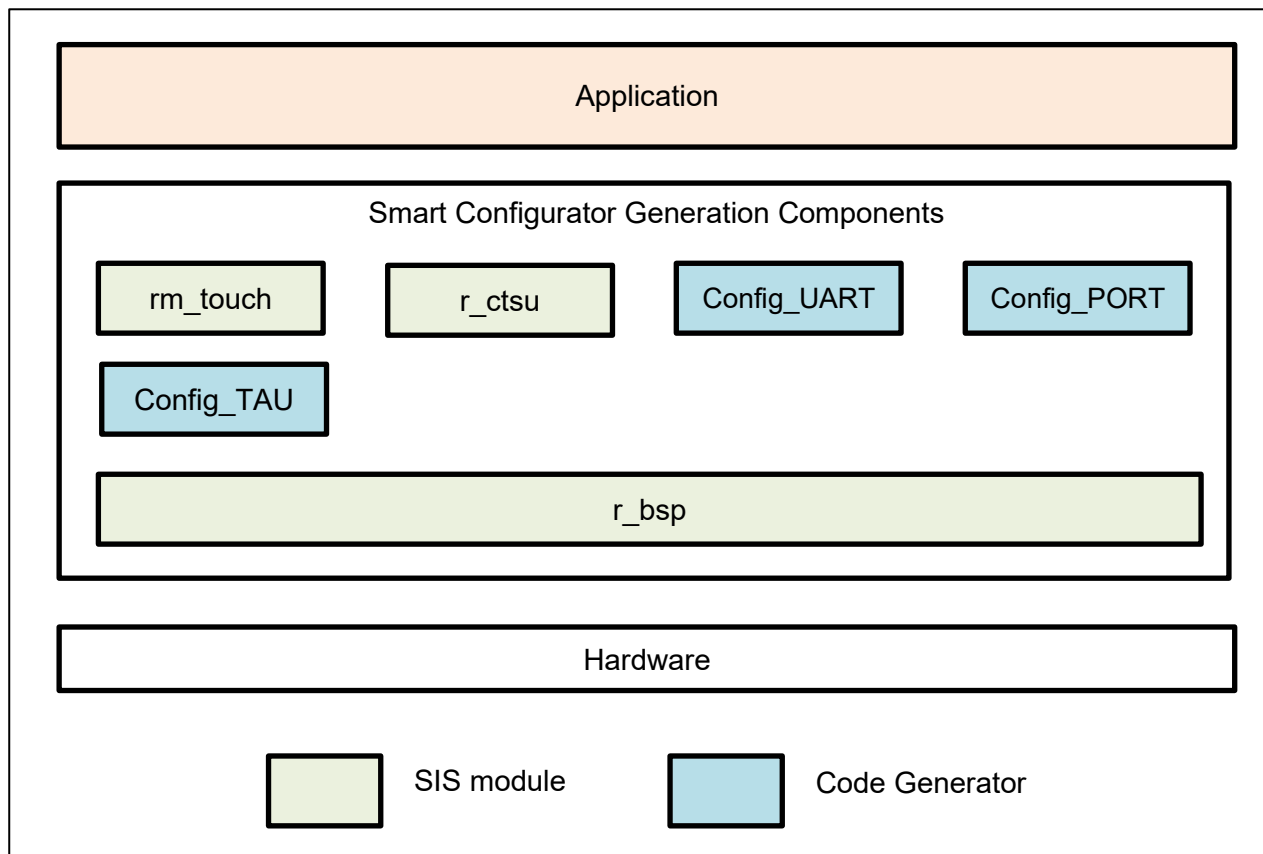
Figure 3-1 Software structure diagram

Table 3-1 shows a list of components and versions. Refer to the smart configurator for component settings.

Table 3-1 Components and versions list

Component	Version	Configuration
✅ Board Support Packages. - v1.50 (r_bsp)	1.50	r_bsp(used)
✅ Capacitive Sensing Unit driver. (r_ctsu)	1.40	r_ctsu(used)
✅ Interval Timer	1.4.0	Config_TAU0_0(TAU0_0: used)
✅ Ports	1.4.0	Config_PORT(PORT: used)
✅ Touch middleware. (rm_touch)	1.40	rm_touch(used)
✅ UART Communication	1.5.0	Config_UART1(UART1: used)

3.2 File structure

This is the file structure of this sample code. The project configuration file and smart configurator generation file of the development environment are omitted.

```
rl78g16_rssk_sample
│
├──QE-Touch
│     rl78g16_rssk_sample_log_tuning20230612172004.log    ・・・QE Tuning log
│     rl78g16_rssk_sample.tifcfg             ・・・Touch interface configuration file
│
├──qe_gen
│     qe_touch_config.c                ・・・Touch configuration source
│     qe_touch_config.h                ・・・Touch configuration header
│     qe_touch_define.h                ・・・Touch define header
│     qe_touch_sample.c                ・・・Touch sample application
│
└──src
      rl78g16_rssk_sample.c            ・・・Main file
      r_rssk_switch_led.c              ・・・Switch & LED function source
      r_rssk_switch_led.h              ・・・Switch & LED function header
      r_rssk_touch_led.c               ・・・Touch electrode LED function source
      r_rssk_touch_led.h               ・・・Touch electrode LED function header
      │
      └──smc_gen
            ├──Config_PORT             ・・・PORT driver folder
            ├──Config_TAU0_0           ・・・Timer driver folder
            ├──Config_UART1            ・・・UART driver folder
            ├──general                 ・・・general setting folder
            ├──rm_touch                ・・・TOUCH SIS module folder
            ├──r_bsp                   ・・・BSP folder
            ├──r_config                ・・・SIS config folder
            ├──r_ctsu                  ・・・CTSU SIS module folder
            └──r_pincfg                ・・・Pin config folder
```

3.3 Constants

Table 3-2 lists the constants.

Table 3-2 List of Constant

Constant Name	Setting Value	Description
File Name : qe_touch_sample.c		
RL78G16_RSSK_TEST	(ELCTRODE_BOARD)	Change the LED control target by specifying ELCTRODE_BOARD or CPU_BOARD.
ELCTRODE_BOARD	(0)	By setting RL78G16_RSSK_TEST, the Self-Capacitance Buttons / Wheel / Slider Board LED can be controlled.
CPU_BOARD	(1)	By setting RL78G16_RSSK_TEST, the CPU board LED can be controlled.
TOUCH_SCAN_INTERVAL_EXAMPLE	(20 * 1000)	Software delay value [unit: µs]
TEST_INTERVAL_EXAMPLE	(1 * 1000)	Initial LED software delay value [unit: µs]
File Name : r_rssk_switch_led.c		
RSSK_SW2_PORT	(P0_bit.no0)	Pointer to port control register connected to SW2
RSSK_SW3_PORT	(P13_bit.no7)	Pointer to port control register connected to SW3
RSSK_LED2_PORT	(P6_bit.no1)	Pointer to port control register connected to LED2
RSSK_LED3_PORT	(P6_bit.no0)	Pointer to port control register connected to LED3
SW_EDGE_RIZE	(0x07U)	Switch rising judgment
SW_EDGE_FALL	(0x08U)	Switch falling judgment
SW_EDGE_BIT_MASK	(0x0FU)	Switch state judgement mask
RSSK_LED_ON	(0x00U)	Turn on the LED
RSSK_LED_OFF	(0x01U)	Turn off the LED

List of Constant (Continue)

File Name : r_rssk_touch_led.c		
LED_COL0	(P1_bit.no2)	Pointer to port control register connected to COL0
LED_COL1	(P1_bit.no3)	Pointer to port control register connected to COL1
LED_COL2	(P1_bit.no4)	Pointer to port control register connected to COL2
LED_COL3	(P1_bit.no5)	Pointer to port control register connected to COL3
LED_ROW0	(P0_bit.no0)	Pointer to port control register connected to ROW0
LED_ROW1	(P6_bit.no1)	Pointer to port control register connected to ROW1
LED_ROW2	(P12_bit.no2)	Pointer to port control register connected to ROW2
LED_ROW3	(P12_bit.no1)	Pointer to port control register connected to ROW3
LED_COL_MAX	(4U)	Number of COL signals
LED_COL_ON	(0x01U)	COL signal ON
LED_COL_OFF	(0x00U)	COL signal OFF
LED_ROW_OFF	(0x01U)	ROW signal OFF
SLIDER_LED_NUM	(5U)	Number of slider LED
SLIDER_RESOLUTION	(100U)	Maximum slider touch result
WHEEL_LED_NUM	(8U)	Number of wheel LED
WHEEL_LED_MSB	(1U << (WHEEL_LED_NUM - 1))	Wheel LED control bit MSB
WHEEL_RESOLUTION_DEGREE	(360U)	Maximum wheel touch result [unit : degree]
WHEEL_POSITION_OFFSET_DEGREE	(112U)	Wheel touch position offset [unit : degree]
ALL_LED_NUM	(16U)	Total number of touch electrode board LEDs
LED_TEST_INTERVAL	(100U)	LED lighting interval time

3.4 Enumerations

Table 3-3 lists the rssk_sw_status_t enum.

Table 3-3 rssk_sw_status_t

Member	Value	Description
RSSK_SW_OFF	0x00	Switch OFF state
RSSK_SW_ON	0x01	Switch OFF state

3.5 Global Variables

Table 3-4 lists the global variables.

Table 3-4 List of Global Variable

Variable Name	Types	Description
File Name : qe_touch_sample.c		
button_status	uint64_t	Button status
slider_position[1]	uint16_t	Slider touch position information
wheel_position[1]	uint16_t	Wheel touch position information
File Name : r_rssk_switch_led.c		
rssk_get_sw2_status	uint8_t	State of switch SW2
rssk_get_sw3_status	uint8_t	State of switch SW3
File Name : r_rssk_touch_led.c		
g_led_drive_colmun	uint8_t	Touch electrode board LED drive information
g_button_idx[3]	uint8_t	Button index array

3.6 Functions

Table 3-5 lists the functions.

Table 3-5 List of Function

Function Name	Description
File Name : qe_touch_sample.c	
qe_touch_main	Main function
qe_touch_delay	Software delay
r_rssk_initialize	Initialization processing of Capacitive Touch Evaluation System
r_rssk_led_test	LED test processing for Capacitive Touch Evaluation System
r_rssk_timer_callback	TAU0 interrupt callback
File Name : r_rssk_switch_led.c	
r_rssk_switch_led_init	CPU board LED initialization processing
r_rssk_switch_led_control	CPU board LED control processing
r_rssk_led2_on	CPU board LED2 turn on
r_rssk_led2_off	CPU board LED2 turn off
r_rssk_led3_on	CPU board LED3 turn on
r_rssk_led3_off	CPU board LED3 turn off
File Name : r_rssk_touch_led.c	
r_rssk_touch_led_test	Touch electrode board LED test pattern processing
r_rssk_touch_led_control	Touch electrode board LED control processing

3.7 List of Peripheral Functions Used and Pins Used

Table 3-6 shows a list of used pins, and Table 3-7 shows a list of handling of unused pins in this sample software.

Table 3-6 List of used pins

Pin No.	Pin Name	I/O	Usage
18	TS00	I/O	CTSU measurement
20	TS01	I/O	
21	TS02	I/O	
22	TS03	I/O	
23	TS04	I/O	
24	TS05	I/O	
25	TS06	I/O	
26	TS07	I/O	
27	TS08	I/O	
28	TS09	I/O	
29	TS10	I/O	
30	TS11	I/O	
31	TS12	I/O	
32	TS13	I/O	
1	TS14	I/O	
19	TSCAP	-	
11	RxD1	I	QE serial communication (SW4 : Left)
12	TxD1	O	
4	P137/SW3	I	LED control
9	P60/LED3	O	
17	P00/LED_ROW0	O	SW4 : Right
10	P61/LED_ROW1	O	-> SW2, SW3, LED2 and LED3 available
5	P122/LED_ROW2	O	SW4 : Left
6	P121/LED_ROW3	O	-> Self-Capacitance Buttons / Wheel / Slider Board LED available
13	P12/LED_COL0	O	
14	P13/LED_COL1	O	
15	P14/LED_COL2	O	
16	P15/LED_COL3	O	

Table 3-7 List of Handling of Unused Pins

Pin No	Pin Name	I/O	Handling
8	VDD	I	Connect the pin to GND via a capacitor (0.1uF).
7	VSS	I	Connect the pin to GND.
Pins than the above		-	Low output

Table 3-8 shows a list of peripheral functions used.

Table 3-8 List of Peripheral Functions Used

Peripheral Function	Usage
CTSU	CTSU measurement
UART1	QE serial monitoring and serial tuning
TAU0	LED control trigger
PORT	LED control

The peripheral function settings using Smart Configurator are shown below.

- UART communication

Use UART1 for serial monitoring of QE for Capacitive Touch. Table 3-9 shows the UART1 settings.

Table 3-9 UART1 Setting

Item	Setting
Operation Clock	CK00
Clock Source	fCLK/2
Transfer mode setting	Single transfer mode
Usable channel	UART1
Transfer rate setting	115200 bps
Callback function setting: Transmit	Transmission end : Enable
Callback function setting : Receive	Reception end : Enable
	Reception error : Enable

- Interval Timer

Use TAU0_0 for LED control. Table 3-10 shows the TAU0_0 settings.

Table 3-10 TAU0 Setting

Item	Setting
Operation Clock	CK00
Clock Source	fCLK/2^8
Interval value (16 bits)	5 ms
Interrupt setting	End of timer channel0 count, generate an interrupt(INTTM00)
	: Enable

- Touch middleware.(rm_touch)

Use rm_touch for touch control. Table 3-11 shows the rm_touch settings. This setting enables QE serial monitoring and serial tuning.

Table 3-11 Touch middleware.(rm_touch) Setting

Item	Setting
Support QE monitor using UART	Enable
Support QE tuning using UART	Enable
UART channel	UART1

3.8   Setting of Option Byte

Make settings related to option bytes.

Set the Clocks configuration tab of the Smart Configurator as follows:

Figure 3-2 Clocks Configuration

Similarly, configure the System configuration tab of the Smart Configurator as follows:
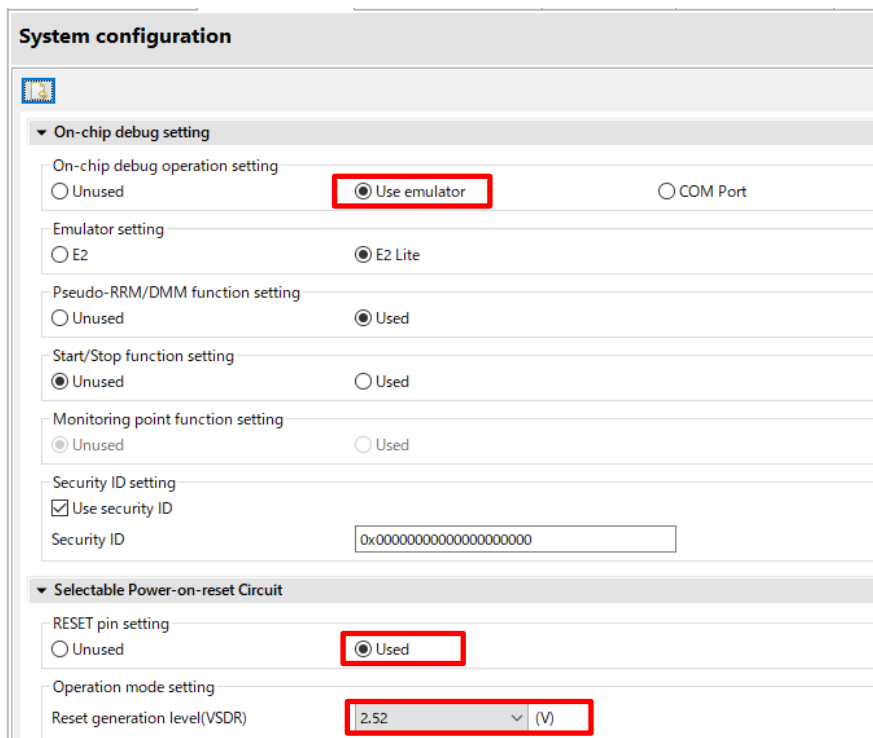

Figure 3-3 System Configuraion

Table 3-12 shows the option byte settings.

Table 3-12 Option Byte Settings

Address	Setting Value	Contents
000C0H/020C0H	11101111B (0xEF)	Disables the watchdog timer. (Counting stopped after reset)
000C1H/020C1H	11111011B (0xFB)	SPOR detection voltage: At rising edge TYP. 2.57 V (2.44 V to 2.68 V) At falling edge TYP. 2.52 V (2.40 V to 2.62 V) Setting of P125/RESET pin: Enables RESET pin
000C2H/020C2H	11111001B (0xF9)	High-speed on-chip oscillator clock (f_{IH}): 16 MHz
000C3H/020C3H	10000101B (0x85)	Enables on-chip debugging

Note : The settings for the watchdog timer are listed in the r_bsp settings list on the Components tab.
         Leave the default (Unsused) and do not change it.

The setting value of the option byte can be checked from the project properties after code generation. Open the project properties and select "C/C++ Build" -> "Settings" to open a "Tool Settings" tab, and select "Linker" -> "Device" and the "User option byte value" and "On-chip debug control value" are displayed.
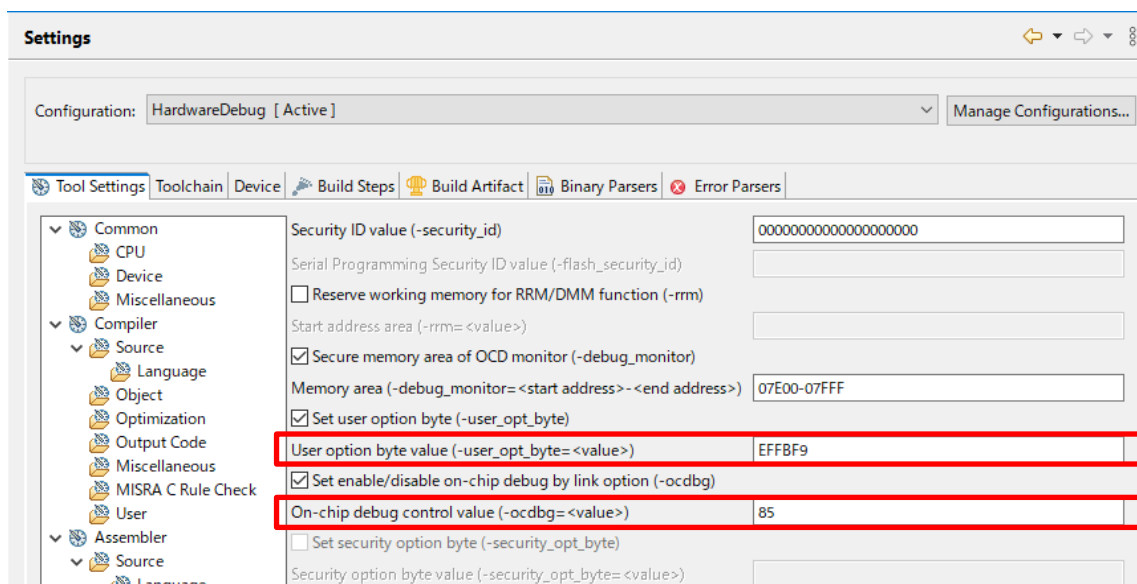
Figure 3-4 User Option Byte Value and On-chip Debug Control Value

3.9   Processing Flowchart

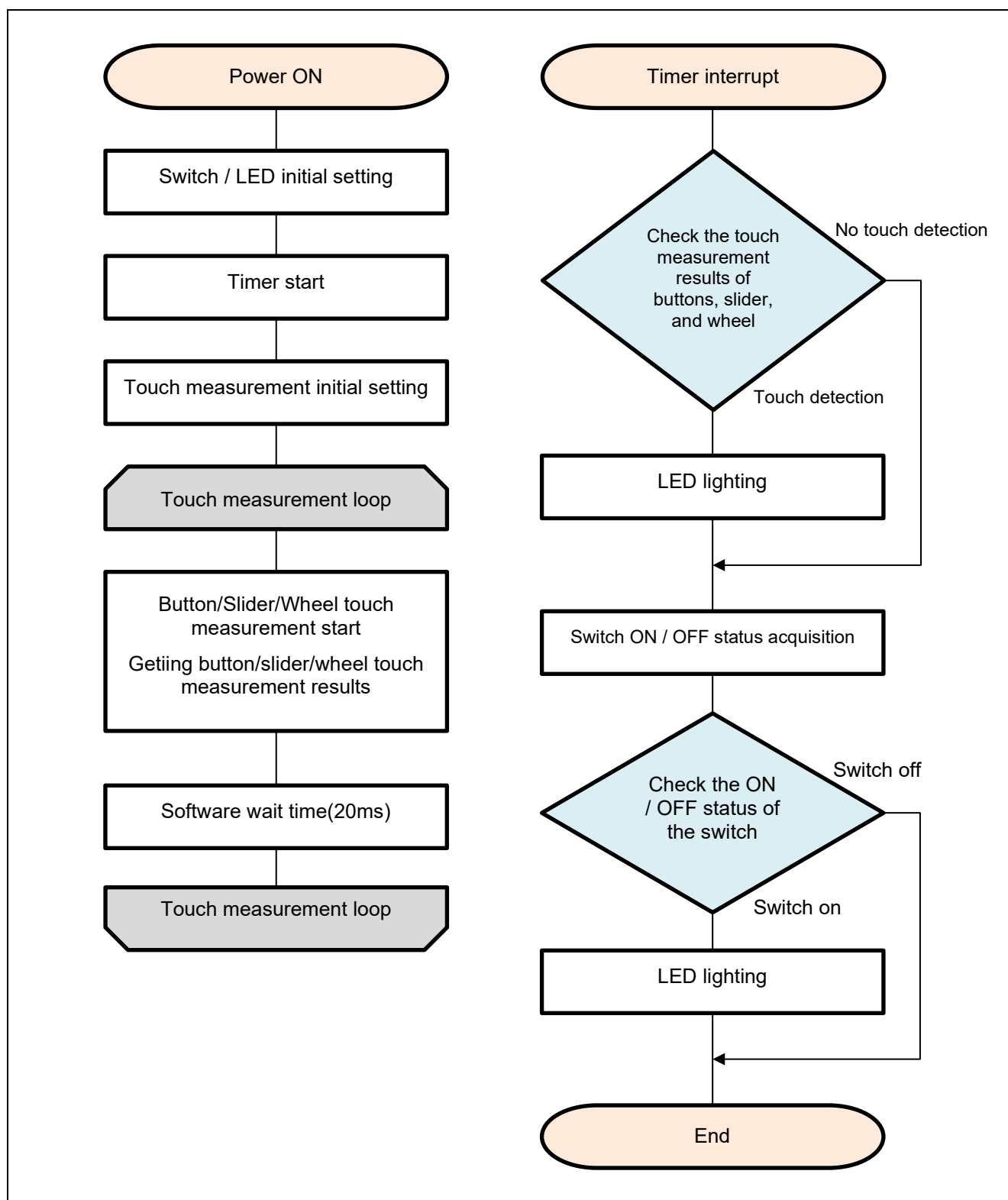Figure 3-5 shows processing flowchart of this sample code.

Figure 3-5 Processing Flowchart (Self-Capacitance Buttons / Wheel / Slider Board)

4. Capacitive Touch Setting

These are the touch interface configuration, configuration (method) settings and tuning results of this sample code. These use the tuning function of QE.
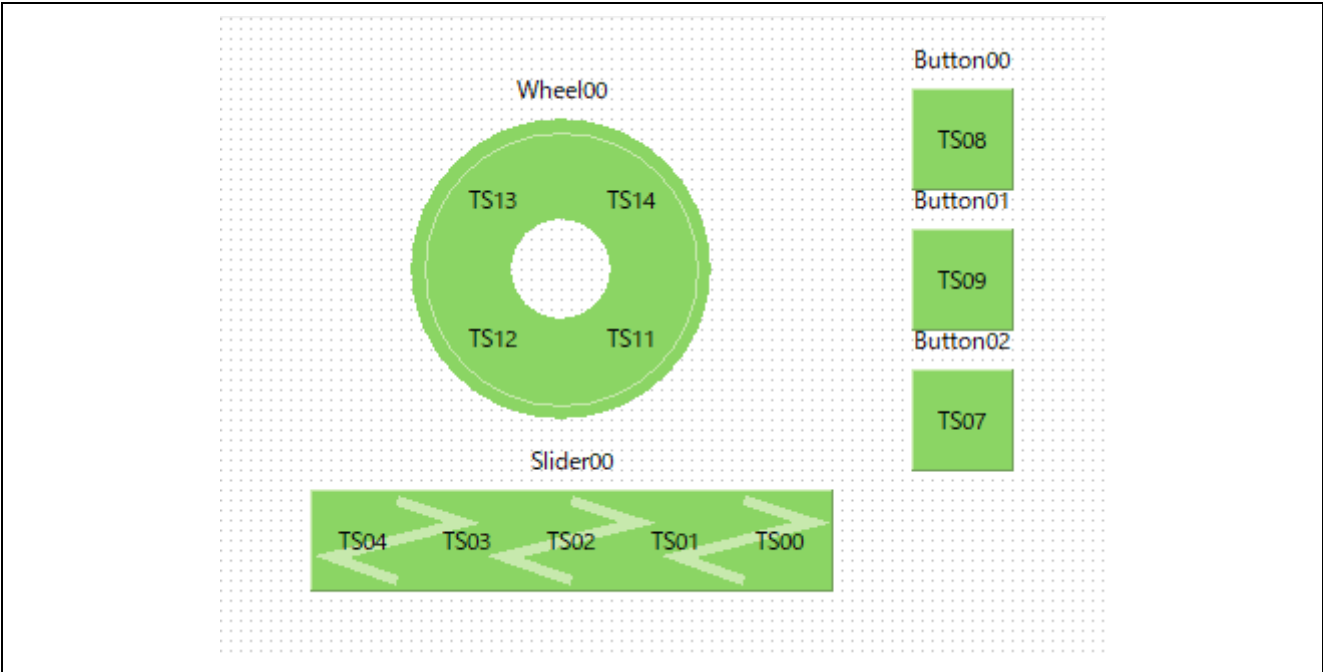
4.1 Touch Interface Configuration

Figure 4-1 Touch interface configuration (Self-Capacitance Buttons / Wheel / Slider Board)

4.2 Configuration (methods) Settings

"config01" assigns 3 buttons, slider and wheel element.

Figure 4-2 Configuration (methods) setting

4.3 Tuning results

Table 4-1 shows tuning results in QE tuning. Sample code operates with the setting values shown in the QE tuning result list.

Since the values in QE tuning result list depend on the operating environment at QE tuning, these values may change at QE tuning again.

Table 4-1 QE tuning result list (Self-Capacitance Buttons / Wheel / Slider Board)

methods	Button name	Touch senser	Parasitic capacitance [pF]	Drive pulse frequency [MHz]	Threshold	Scan time [ms]	so	snum	sdpa
config01	Button00	TS08	20.992	0.943 (BASE: 1.0)	723	0.592	0x06C	0x01	0x07
config01	Button01	TS09	19.213	0.943 (BASE: 1.0)	726	0.592	0x05A	0x01	0x07
config01	Button02	TS07	19.096	0.943 (BASE: 1.0)	701	0.592	0x058	0x01	0x07
config01	Slider00	TS04	16.08	0.943 (BASE: 1.0)	457	0.592	0x03D	0x01	0x07
config01	Slider00	TS03	17.434	0.943 (BASE: 1.0)	457	0.592	0x049	0x01	0x07
config01	Slider00	TS02	17.812	0.943 (BASE: 1.0)	457	0.592	0x04E	0x01	0x07
config01	Slider00	TS01	18.449	0.943 (BASE: 1.0)	457	0.592	0x054	0x01	0x07
config01	Slider00	TS00	20.954	0.943 (BASE: 1.0)	457	0.592	0x06D	0x01	0x07
config01	Wheel00	TS13	23.047	0.943 (BASE: 1.0)	513	0.592	0x084	0x01	0x07
config01	Wheel00	TS14	24.848	0.943 (BASE: 1.0)	513	0.592	0x093	0x01	0x07
config01	Wheel00	TS11	24.132	0.943 (BASE: 1.0)	513	0.592	0x08E	0x01	0x07
config01	Wheel00	TS12	22.221	0.943 (BASE: 1.0)	513	0.592	0x07C	0x01	0x07

so   : Variables for sensor offset settings

snum : Variables for setting the measurement period

sdpa : Clock division setting variable

4.4   Sensitivity adjustment

Button sensitivity adjustment uses QE for Capacitive Touch. The sensitivity adjustment method is as follows.

- The method using monitoring function of QE for Capacitive Touch

Follow the tutorial from the "CapTouch Workflow (QE)" of QE for Capacitive Touch.

- Real-time change method using monitoring function of QE for Capacitive Touch

Display the Cap Touch parameter list of QE for Capacitive Touch and adjust it by the following steps.

1.   Select the touch I/F corresponding to the button you want to adjust.
2.   Click [Enable Monitoring] icon to start monitoring.
      When monitoring is enabled, the CapTouch parameter item is displayed.
3.   Click [Write Value to the Target Board] to enable.
4.   Change the value of [Touch Threshold].
5.   Repeat steps 4 to adjust the sensitivity.

After completing the sensitivity adjustment, reflect the adjustment result in the source code by the following steps.

6.   Click [Output Parameter Files] to generate the parameter file.
7.   Build the project using the IDE (e^2 studio as an example).
8.   Write the program to the MCU using the IDE (e^2 studio as an example).
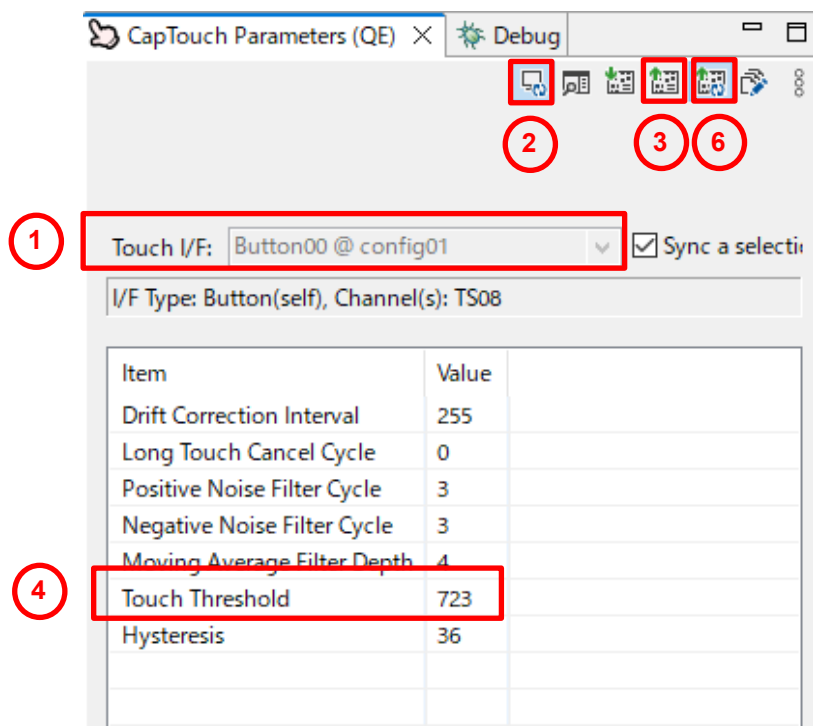
- How to change the code manually

It can be adjusted by changing member variables of structure variable g_qe_touch_button_cfg_config01.

The variables to change are:

- threshold : Touch detection threshold

5. Support

For information on capacitive touch, download tools and documentation, and technical support, please visit the website below

RL78/G16 Capacitive Touch Evaluation System   https://www.renesas.com/rssk-touch-rl78G16

Application Note RL78 Family Using the standalone version of QE to Develop Capacitive Touch Applications (R01AN6574)

https://www.renesas.com/us/en/document/apn/rl78-family-using-standalone-version-qe-develop-capacitive-touch-applications-rev100

QE for Capacitive Touch   renesas.com/qe-capacitive-touch

Renesas support   renesas.com/support

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	23.Jun.2023	-	First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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